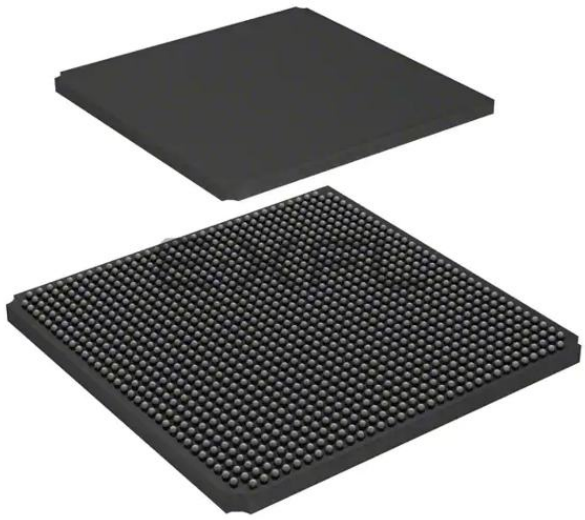
Lattice Semiconductor Corporation - LFE2M70E-5F1152I Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

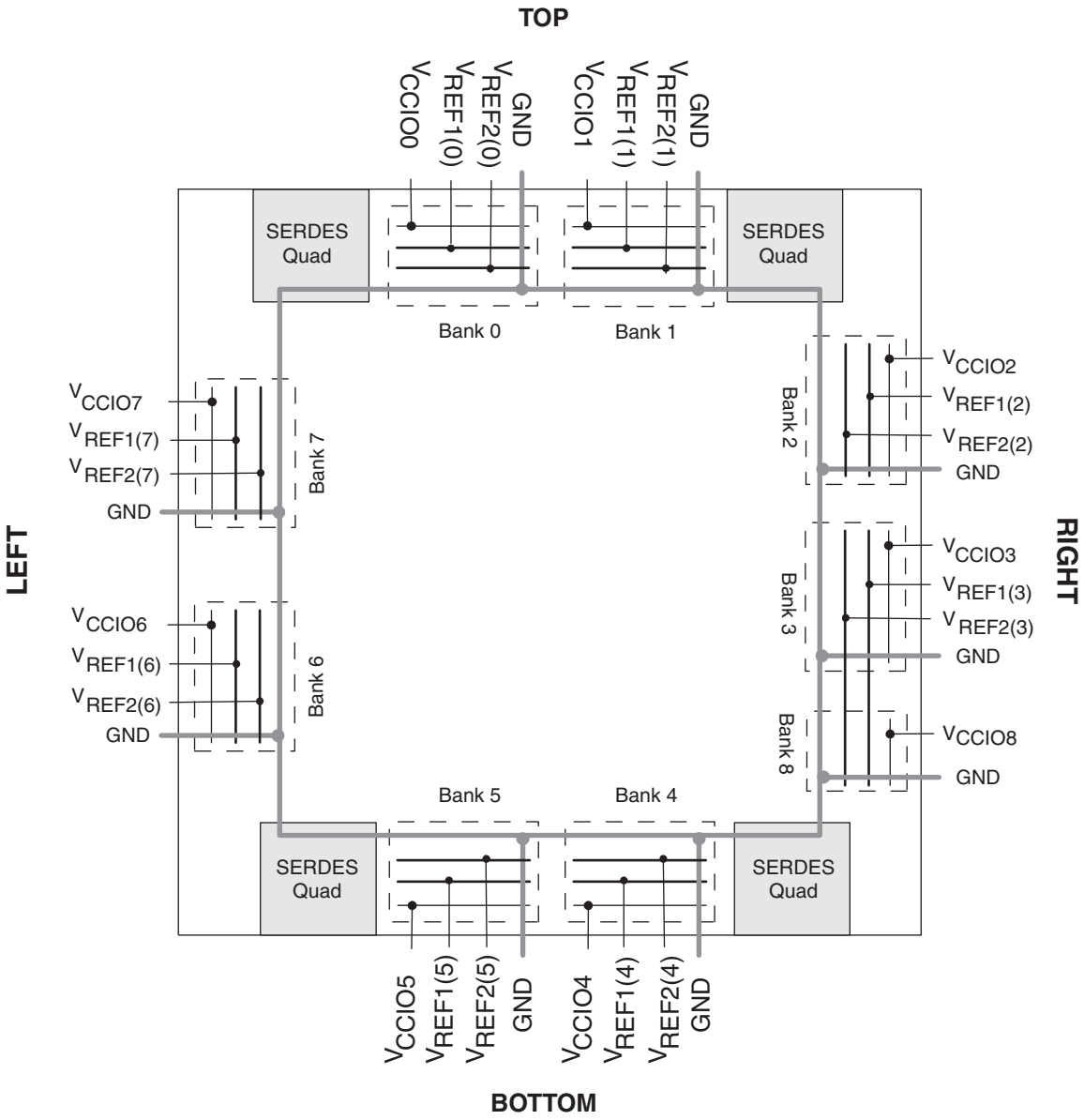
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	8375
Number of Logic Elements/Cells	67000
Total RAM Bits	4642816
Number of I/O	436
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA
Supplier Device Package	1152-FPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m70e-5f1152i

Figure 2-38. LatticeECP2M Banks



LatticeECP2/M devices contain two types of sysI/O buffer pairs.

1. **Top (Bank 0 and Bank 1) sysI/O Buffer Pairs (Single-Ended Outputs Only)**
   The sysI/O buffer pairs in the top banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). One of the referenced input buffers can also be configured as a differential input.

   The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. **Bottom (Bank 4 and Bank 5) sysI/O Buffer Pairs (Single-Ended Outputs Only)**
   The sysI/O buffer pairs in the bottom banks of the device consist of two single-ended output drivers and two

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP2/M devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP2/M devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support both byte-wide and serial configuration, including the standard SPI Flash interface. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In- System Configuration specification. The sysCONFIG port is a 20-pin interface with six I/Os used as dedicated pins with the remainder used as dual-use pins. See TN1108, LatticeECP2/M sysCONFIG Usage Guide for more information about using the dual-use pins as general purpose I/Os.

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

Enhanced Configuration Option

LatticeECP2/M devices have enhanced configuration features such as: decryption support, TransFR™ I/O and dual boot image support.

1. **Decryption Support**
   LatticeECP2/M devices provide on-chip, One Time Programmable (OTP) non-volatile key storage to support decryption of a 128-bit AES encrypted bitstream, securing designs and deterring design piracy.

2. **TransFR (Transparent Field Reconfiguration)**
   TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM® command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, Minimizing System Interruption During Configuration Using TransFR Technology, for details.

3. **Dual Boot Image Support**
   Dual boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the LatticeECP2/M can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the LatticeECP2/M device can revert back to the original backup configuration and try again. This all can be done without power cycling the system.

For more information about device configuration, please see the list of additional technical documentation at the end of this data sheet.

Soft Error Detect (SED) Support

LatticeECP2/M devices have dedicated logic to perform CRC checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the LatticeECP2 device can also be programmed

for checking soft errors (SED) in SRAM. SED can be run on a programmed device when the user logic is not active. If a soft error occurs, during user mode (normal operation) the device can be programmed to either reload from a known good boot image or generate an error signal.

For further information about Soft Error Detect (SED) support, please see the list of additional technical documentation at the end of this data sheet.

External Resistor

LatticeECP2/M devices require a single external, 10K ohm ±1% value between the XRES pin and ground. Device configuration will not be completed if this resistor is missing. There is no boundary scan register on the external resistor pad.

On-Chip Oscillator

Every LatticeECP2/M device has an internal CMOS oscillator which is used to derive a Master Clock for configuration. The oscillator and the Master Clock run continuously and are available to user logic after configuration is completed. The software default value of the Master Clock is 2.5MHz. Table 2-16 lists all the available Master Configuration Clock frequencies for normal non-encrypted mode and encrypted mode. When a different Master Clock is selected during the design process, the following sequence takes place:

1. Device powers up with a Master Clock frequency of 3.1MHz.
2. During configuration, users select a different master clock frequency.
3. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.
4. If the user does not select a master clock frequency, then the configuration bitstream defaults to the Master Clock frequency of 2.5MHz.

This internal CMOS oscillator is available to the user by routing it as an input clock to the clock tree. For further information about the use of this oscillator for configuration or user mode, please see the list of additional technical documentation at the end of this data sheet.

Table 2-16. Selectable Master Clock (CCLK) Frequencies During Configuration

Non-Encrypted Mode CCLK (MHz)			Encrypted Mode CCLK (MHz)
2.5[1]	13.0	45.0	2.5[1]
4.3	15.0	55.0	5.4
5.4	20.0	60.0	10.0
6.9	26.0	—	—
8.1	30.0	—	—
9.2	34.0	—	—
10.0	41.0	130.0	—

1. Software default frequency.

Density Shifting

The LatticeECP2/M family is designed to ensure that different density devices in the same family and in the same package have the same pinout. Furthermore, the architecture ensures a high success rate when performing design migration from lower density devices to higher density devices. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likelihood of success in each case. Design migration between LatticeECP2 and LatticeECP2M families is not possible. For specific requirements relating to sysCONFIG pins of the ECP2M50, M70 and M100, see the Logic Signal Connections tables.

sysI/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}[1] (mA)	I_{OH}[1] (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	0.35 V_{CCIO}	0.65 V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	0.35 V_{CCIO}	0.65 V_{CCIO}	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2	-0.3	0.35 V_{CC}	0.65 V_{CC}	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	0.3 V_{CCIO}	0.5 V_{CCIO}	3.6	0.1 V_{CCIO}	0.9 V_{CCIO}	1.5	-0.5
SSTL3 Class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 Class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 Class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
							12	-12
SSTL2 Class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
							20	-20
SSTL18 Class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
SSTL18 Class II	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.28	V_{CCIO} - 0.28	8	-8
							11	-11
HSTL Class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	4	-4
							8	-8
HSTL18 Class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
							12	-12
HSTL18 Class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA, where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

Register-to-Register Performance (Continued)

Function	-7 Timing	Units
36x36 Multiplier (All Registers)	372	MHz
18x18 Multiplier/Accumulate (Input and Output Registers)	295	MHz
18x18 Multiplier-Add/Sub-Sum (All Registers)	420	MHz
DSP IP Functions		
16-Tap Fully-Parallel FIR Filter	304	MHz
1024-pt, Radix 4, Decimation in Frequency FFT	227	MHz
8x8 Matrix Multiplier	223	MHz

Derating Timing Tables

Logic timing provided in the following sections of this data sheet and the Diamond design tool are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best case process, can be much better than the values given in the tables. The Diamond design tool can provide logic timing numbers at a particular temperature and voltage.

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{SUE}	Clock to Data Setup - PIO Input Register	LFE2-6	0.00	—	0.00	—	0.00	—	ns
		LFE2-12	0.00	—	0.00	—	0.00	—	ns
		LFE2-20	0.00	—	0.00	—	0.00	—	ns
		LFE2-35	0.00	—	0.00	—	0.00	—	ns
		LFE2-50	0.00	—	0.00	—	0.00	—	ns
		LFE2-70	0.00	—	0.00	—	0.00	—	ns
		LFE2M20	0.00	—	0.00	—	0.00	—	ns
		LFE2M35	0.00	—	0.00	—	0.00	—	ns
		LFE2M50	0.00	—	0.00	—	0.00	—	ns
		LFE2M70	0.00	—	0.00	—	0.00	—	ns
		LFE2M100	0.00	—	0.00	—	0.00	—	ns
t_{HE}	Clock to Data Hold - PIO Input Register	LFE2-6	0.90	—	1.10	—	1.30	—	ns
		LFE2-12	0.90	—	1.10	—	1.30	—	ns
		LFE2-20	0.90	—	1.10	—	1.30	—	ns
		LFE2-35	0.90	—	1.10	—	1.30	—	ns
		LFE2-50	0.90	—	1.10	—	1.30	—	ns
		LFE2-70	0.90	—	1.10	—	1.30	—	ns
		LFE2M20	0.90	—	1.10	—	1.30	—	ns
		LFE2M35	0.90	—	1.10	—	1.30	—	ns
		LFE2M50	1.20	—	1.40	—	1.60	—	ns
		LFE2M70	1.20	—	1.40	—	1.60	—	ns
		LFE2M100	1.20	—	1.40	—	1.60	—	ns
t_{SU_DELE}	Clock to Data Setup - PIO Input Register with Data Input Delay	LFE2-6	1.00	—	1.30	—	1.60	—	ns
		LFE2-12	1.00	—	1.30	—	1.60	—	ns
		LFE2-20	1.00	—	1.30	—	1.60	—	ns
		LFE2-35	1.00	—	1.30	—	1.60	—	ns
		LFE2-50	1.00	—	1.30	—	1.60	—	ns
		LFE2-70	1.00	—	1.30	—	1.60	—	ns
		LFE2M20	1.20	—	1.60	—	1.90	—	ns
		LFE2M35	1.20	—	1.60	—	1.90	—	ns
		LFE2M50	1.20	—	1.60	—	1.90	—	ns
		LFE2M70	1.20	—	1.60	—	1.90	—	ns
		LFE2M100	1.20	—	1.60	—	1.90	—	ns

DLL Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Typ.	Max.	Units
f_{REF}	Input reference clock frequency (on-chip or off-chip)	100	—	500	MHz
f_{FB}	Feedback clock frequency (on-chip or off-chip)	100	—	500	MHz
f_{CLKOP}[1]	Output clock frequency, CLKOP	100	—	500	MHz
f_{CLKOS}[2]	Output clock frequency, CLKOS	25	—	500	MHz
t_{PJIT}	Output clock period jitter (clean input)		—	250	ps p-p
t_{CYJIT}	Output clock cycle to cycle jitter (clean input)			250	ps p-p
t_{DUTY}	Output clock duty cycle (at 50% levels, 50% duty cycle input clock, 50% duty cycle circuit turned off, time reference delay mode)	35		65	%
$t_{DUTYTRD}$	Output clock duty cycle (at 50% levels, arbitrary duty cycle input clock, 50% duty cycle circuit enabled, time reference delay mode)	40		60	%
$t_{DUTYCIR}$	Output clock duty cycle (at 50% levels, arbitrary duty cycle input clock, 50% duty cycle circuit enabled, clock injection removal mode)	40		60	%
t_{SKEW}[3]	Output clock to clock skew between two outputs with the same phase setting	—	—	100	ps
t_{PWH}	Input clock minimum pulse width high (at 80% level)	750	—	—	ps
t_{PWL}	Input clock minimum pulse width low (at 20% level)	750	—	—	ps
t_{INSTB}	Input clock period jitter	—	—	+/-250	ps
t_{LOCK}	DLL lock time	18,500	—	—	cycles
t_{RSWD}	Digital reset minimum pulse width (at 80% level)	3	—	—	ns
t_{PA}	Delay step size	16.5	42	59.4	ps
t_{RANGE1}	Max. delay setting for single delay block (144 taps)	2.376	6	8.553	ns
t_{RANGE4}	Max. delay setting for four chained delay blocks	9.504	24	34.214	ns

1. CLKOP runs at the same frequency as the input clock.
2. CLKOS minimum frequency is obtained with divide by 4.
3. This is intended to be a “path-matching” design guideline and is not a measurable specification.

LatticeECP2/M sysCONFIG Port Timing Specifications (Continued)

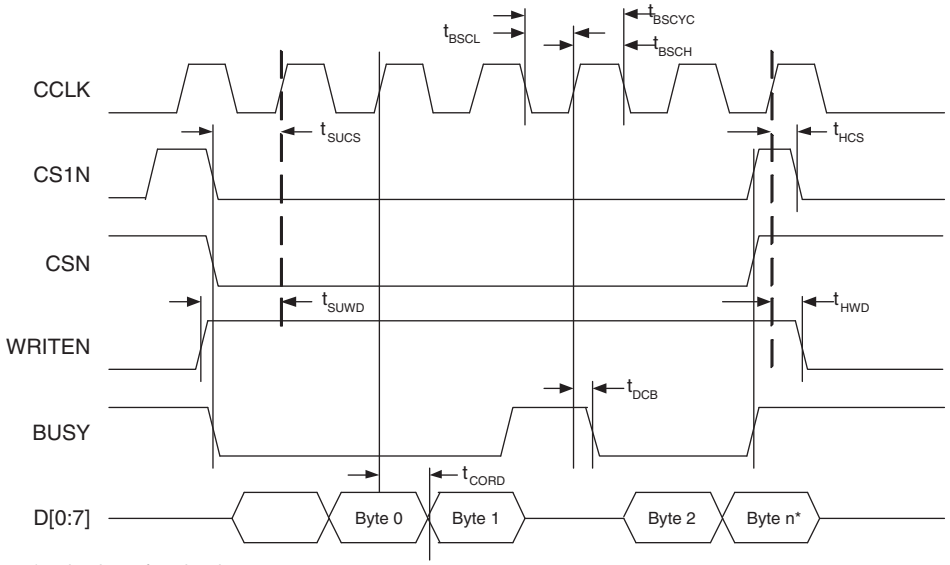
Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
f_{MAXSPI}	Max. CCLK Frequency - SPI Flash Read Opcode (0x03) (SPIFASTN = 1)	—	20	MHz
	Max. CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN = 0)	—	50	MHz
	Max. CCLK Frequency - Encrypted Bitstream	—	10	MHz
t_{SUSPI}	SOSPI Data Setup Time Before CCLK	7	—	ns
t_{HSPI}	SOSPI Data Hold Time After CCLK	2	—	ns
t_{SUMCDI}	DI Setup to CCLK	7	—	ns
t_{HMCDI}	DI Hold from CCLK	1	—	ns

1. Re-toggling the PROGRAMN pin is not permitted until the INITN pin is high. Avoid consecutive toggling of the PROGRAMN.
2. For SED (Soft Error Detect), the SEDCLKIN operating frequency must be at least 20MHz. SEDCLKIN is derived from Master Clock Frequency that has a +/-30% variation..

Parameter	Min.	Max.	Units
Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
Duty Cycle	40	60	%

Figure 3-14. sysCONFIG Parallel Port Read Cycle



*n = last byte of read cycle.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A6	PT21A	0		T	PT30A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
C7	PT17B	0		C	PT26B	0		C
D10	PT18B	0		C	PT27B	0		C
C6	PT17A	0		T	PT26A	0		T
E10	PT18A	0		T	PT27A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F10	PT15B	0		C	PT24B	0		C
B6	PT16B	0		C	PT25B	0		C
D9	PT15A	0		T	PT24A	0		T
B5	PT16A	0		T	PT25A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
A5	PT13B	0		C	PT22B	0		C
F9	PT14B	0		C	PT23B	0		C
A4	PT13A	0		T	PT22A	0		T
E9	PT14A	0		T	PT23A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
G8	PT11B	0		C	PT20B	0		C
A3	PT12B	0		C	PT21B	0		C
E8	PT11A	0		T	PT20A	0		T
A2	PT12A	0		T	PT21A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
-	-	-			VCCIO0	0		
C3	PT10B	0		C	PT10B	0		C
B3	PT10A	0		T	PT10A	0		T
-	-	-			GNDIO0	-		
E7	PT8B	0		C	PT8B	0		C
F8	PT9B	0		C	PT9B	0		C
F7	PT8A	0		T	PT8A	0		T
D7	PT9A	0		T	PT9A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
D4	PT6B	0		C	PT6B	0		C
D5	PT7B	0		C	PT7B	0		C
C4	PT6A	0		T	PT6A	0		T
D6	PT7A	0		T	PT7A	0		T
GNDIO	GNDIO0	-			GNDIO	-		
J7	PT4B	0		C	PT4B	0		C
B2	PT5B	0		C	PT5B	0		C
H7	PT4A	0		T	PT4A	0		T
B1	PT5A	0		T	PT5A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
D1	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
D3	PT3B	0		C	PT3B	0		C
C1	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C8	PT29B	0		C	PT38B	0		C
D8	PT29A	0		T	PT38A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
D10	PT27B	0		C	PT36B	0		C
E10	PT27A	0		T	PT36A	0		T
C7	PT26B	0		C	PT35B	0		C
C6	PT26A	0		T	PT35A	0		T
VCCIO	VCCIO0	0			VCCIO	0		
B6	PT25B	0		C	PT34B	0		C
B5	PT25A	0		T	PT34A	0		T
F10	PT24B	0		C	PT33B	0		C
D9	PT24A	0		T	PT33A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
F9	PT23B	0		C	PT32B	0		C
E9	PT23A	0		T	PT32A	0		T
A5	PT22B	0		C	PT31B	0		C
A4	PT22A	0		T	PT31A	0		T
VCCIO	VCCIO0	0			VCCIO	0		
A3	PT21B	0		C	PT30B	0		C
A2	PT21A	0		T	PT30A	0		T
G8	PT20B	0		C	PT29B	0		C
E8	PT20A	0		T	PT29A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
VCCIO	VCCIO0	0			VCCIO	0		
C3	PT10B	0		C	PT10B	0		C
B3	PT10A	0		T	PT10A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
F8	PT9B	0		C	PT9B	0		C
D7	PT9A	0		T	PT9A	0		T
E7	PT8B	0		C	PT8B	0		C
VCCIO	VCCIO0	0			VCCIO	0		
F7	PT8A	0		T	PT8A	0		T
D5	PT7B	0		C	PT7B	0		C
D6	PT7A	0		T	PT7A	0		T
D4	PT6B	0		C	PT6B	0		C
C4	PT6A	0		T	PT6A	0		T
GNDIO	GNDIO0	-			GNDIO0	0		
B2	PT5B	0		C	PT5B	0		C
B1	PT5A	0		T	PT5A	0		T
J7	PT4B	0		C	PT4B	0		C
VCCIO	VCCIO0	0			VCCIO	0		
H7	PT4A	0		T	PT4A	0		T
D3	PT3B	0		C	PT3B	0		C
C2	PT3A	0		T	PT3A	0		T
D1	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
C1	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
W5	PL71B	6	LDQ75	C (LVDS)*	PL84B	6	LDQ88	C (LVDS)*
AC1	PL72A	6	LDQ75	T	PL85A	6	LDQ88	T
AD1	PL72B	6	LDQ75	C	PL85B	6	LDQ88	C
VCCIO	VCCIO6	6			VCCIO6	6		
Y6	PL73A	6	LDQ75	T (LVDS)*	PL86A	6	LDQ88	T (LVDS)*
Y5	PL73B	6	LDQ75	C (LVDS)*	PL86B	6	LDQ88	C (LVDS)*
AE2	PL74A	6	LDQ75	T	PL87A	6	LDQ88	T
AD2	PL74B	6	LDQ75	C	PL87B	6	LDQ88	C
GND	GNDIO6	-			GNDIO6	-		
AB3	PL75A	6	LDQS75	T (LVDS)*	PL88A	6	LDQS88	T (LVDS)*
AB2	PL75B	6	LDQ75	C (LVDS)*	PL88B	6	LDQ88	C (LVDS)*
W7	PL76A	6	LDQ75	T	PL89A	6	LDQ88	T
VCCIO	VCCIO6	6			VCCIO6	6		
W8	PL76B	6	LDQ75	C	PL89B	6	LDQ88	C
Y7	PL77A	6	LDQ75	T (LVDS)*	PL90A	6	LDQ88	T (LVDS)*
Y8	PL77B	6	LDQ75	C (LVDS)*	PL90B	6	LDQ88	C (LVDS)*
AC2	PL78A	6	LDQ75	T	PL91A	6	LDQ88	T
GND	GNDIO6	-			GNDIO6	-		
AD3	PL78B	6	LDQ75	C	PL91B	6	LDQ88	C
AC3	TCK	-			TCK	-		
AA8	TDI	-			TDI	-		
AB4	TMS	-			TMS	-		
AA5	TDO	-			TDO	-		
AB5	VCCJ	-			VCCJ	-		
AE3	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T
AF3	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C
AC4	PB3A	5	BDQ6	T	PB3A	5	BDQ6	T
AD4	PB3B	5	BDQ6	C	PB3B	5	BDQ6	C
AE4	PB4A	5	BDQ6	T	PB4A	5	BDQ6	T
AF4	PB4B	5	BDQ6	C	PB4B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
V9	PB5A	5	BDQ6	T	PB5A	5	BDQ6	T
W9	PB5B	5	BDQ6	C	PB5B	5	BDQ6	C
GND	GNDIO5	-			GNDIO5	-		
AA6	PB6A	5	BDQS6	T	PB6A	5	BDQS6	T
AB6	PB6B	5	BDQ6	C	PB6B	5	BDQ6	C
AC5	PB7A	5	BDQ6	T	PB7A	5	BDQ6	T
AD5	PB7B	5	BDQ6	C	PB7B	5	BDQ6	C
AA7	PB8A	5	BDQ6	T	PB8A	5	BDQ6	T
AB7	PB8B	5	BDQ6	C	PB8B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
AE5	PB9A	5	BDQ6	T	PB9A	5	BDQ6	T
AF5	PB9B	5	BDQ6	C	PB9B	5	BDQ6	C
AC7	PB10A	5	BDQ6	T	PB10A	5	BDQ6	T
AD7	PB10B	5	BDQ6	C	PB10B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A7	PT35B	0		C	PT44B	0		C
B7	PT35A	0		T	PT44A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F12	PT34B	0		C	PT43B	0		C
D10	PT34A	0		T	PT43A	0		T
H11	PT33B	0		C	PT42B	0		C
G11	PT33A	0		T	PT42A	0		T
GND	GNDIO0	-			GNDIO0	-		
A6	PT32B	0		C	PT41B	0		C
B6	PT32A	0		T	PT41A	0		T
D8	PT31B	0		C	PT40B	0		C
C8	PT31A	0		T	PT40A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F11	PT30B	0		C	PT39B	0		C
E10	PT30A	0		T	PT39A	0		T
E9	PT29B	0		C	PT38B	0		C
D9	PT29A	0		T	PT38A	0		T
G10	PT28B	0		C	PT37B	0		C
GND	GNDIO0	-			GNDIO0	-		
H10	PT28A	0		T	PT37A	0		T
A5	PT27B	0		C	PT36B	0		C
B5	PT27A	0		T	PT36A	0		T
C7	PT26B	0		C	PT35B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
D7	PT26A	0		T	PT35A	0		T
E8	PT25B	0		C	PT34B	0		C
F10	PT25A	0		T	PT34A	0		T
F8	PT24B	0		C	PT33B	0		C
H9	PT24A	0		T	PT33A	0		T
C5	PT23B	0		C	PT32B	0		C
GND	GNDIO0	-			GNDIO0	-		
D5	PT23A	0		T	PT32A	0		T
B4	PT22B	0			PT31B	0		
VCCIO	VCCIO0	0			VCCIO0	0		
GND	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
GND	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
C4	PT10B	0		C	PT10B	0		C
GND	GNDIO0	-			GNDIO0	-		
C3	PT10A	0		T	PT10A	0		T
A4	PT9B	0		C	PT9B	0		C
A3	PT9A	0		T	PT9A	0		T
B3	PT8B	0		C	PT8B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
B2	PT8A	0		T	PT8A	0		T

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
Y10	VCC	-		
Y11	VCC	-		
Y12	VCC	-		
Y13	VCC	-		
Y18	VCC	-		
Y19	VCC	-		
Y20	VCC	-		
J13	VCCIO0	0		
J14	VCCIO0	0		
K12	VCCIO0	0		
K13	VCCIO0	0		
K14	VCCIO0	0		
K15	VCCIO0	0		
J17	VCCIO1	1		
J18	VCCIO1	1		
J20	VCCIO1	1		
K17	VCCIO1	1		
K18	VCCIO1	1		
K20	VCCIO1	1		
L21	VCCIO2	2		
M21	VCCIO2	2		
M22	VCCIO2	2		
N21	VCCIO2	2		
N22	VCCIO2	2		
R21	VCCIO2	2		
U21	VCCIO3	3		
U22	VCCIO3	3		
V21	VCCIO3	3		
V22	VCCIO3	3		
W21	VCCIO3	3		
Y22	VCCIO3	3		
AA16	VCCIO4	4		
AA17	VCCIO4	4		
AA18	VCCIO4	4		
AA19	VCCIO4	4		
AB17	VCCIO4	4		
AB18	VCCIO4	4		
AA12	VCCIO5	5		
AA13	VCCIO5	5		
AA14	VCCIO5	5		
AB12	VCCIO5	5		
AB13	VCCIO5	5		
AB14	VCCIO5	5		

LFE2M-20E/SE and LFE2M-35E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A7	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
C6	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
B4	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B3	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
A4	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
C3	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		
GNDIO	GNDIO1	-			GNDIO1	-		
VCCIO	VCCIO1	1			VCCIO1	1		
GNDIO	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
G10	VCCPLL	-			VCCPLL	-		
G7	VCC	-			VCC	-		
G9	VCC	-			VCC	-		
H7	VCC	-			VCC	-		
J10	VCC	-			VCC	-		
K10	VCC	-			VCC	-		
K8	VCC	-			VCC	-		
E7	VCCIO0	0			VCCIO0	0		
VCCIO	VCCIO0	0			VCCIO0	0		
E10	VCCIO1	1			VCCIO1	1		
VCCIO	VCCIO1	1			VCCIO1	1		
E14	VCCIO2	2			VCCIO2	2		
G12	VCCIO2	2			VCCIO2	2		
VCCIO	VCCIO2	2			VCCIO2	2		
K12	VCCIO3	3			VCCIO3	3		
M14	VCCIO3	3			VCCIO3	3		
VCCIO	VCCIO3	3			VCCIO3	3		
M10	VCCIO4	4			VCCIO4	4		
P12	VCCIO4	4			VCCIO4	4		
VCCIO	VCCIO4	4			VCCIO4	4		
M7	VCCIO5	5			VCCIO5	5		
P5	VCCIO5	5			VCCIO5	5		
VCCIO	VCCIO5	5			VCCIO5	5		
K5	VCCIO6	6			VCCIO6	6		
M3	VCCIO6	6			VCCIO6	6		
VCCIO	VCCIO6	6			VCCIO6	6		
E3	VCCIO7	7			VCCIO7	7		
G5	VCCIO7	7			VCCIO7	7		
VCCIO	VCCIO7	7			VCCIO7	7		
T15	VCCIO8	8			VCCIO8	8		
VCCIO	VCCIO8	8			VCCIO8	8		
G8	VCCAUX	-			VCCAUX	-		
H10	VCCAUX	-			VCCAUX	-		
J7	VCCAUX	-			VCCAUX	-		
K9	VCCAUX	-			VCCAUX	-		
A1	GND	-			GND	-		
A15	GND	-			GND	-		
A16	GND	-			GND	-		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A21	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		
A22	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
C21	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
B19	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B18	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
A19	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
C18	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		
D23	PT73B	1		C	PT82B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
E21	PT73A	1		T	PT82A	1		T
D26	PT72B	1		C	PT81B	1		C
E26	PT72A	1		T	PT81A	1		T
E23	PT71B	1		C	PT80B	1		C
-	-	-			VCCIO1	1		
G22	PT71A	1		T	PT80A	1		T
VCCIO	VCCIO1	1			-	-		
D22	PT70B	1		C	PT79B	1		C
F21	PT70A	1		T	PT79A	1		T
G18	PT69B	1		C	PT78B	1		C
H18	PT69A	1		T	PT78A	1		T
D20	PT68B	1		C	PT77B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
D21	PT68A	1		T	PT77A	1		T
E20	PT67B	1		C	PT76B	1		C
E19	PT67A	1		T	PT76A	1		T
D19	PT66B	1		C	PT75B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
E18	PT66A	1		T	PT75A	1		T
D18	PT65B	1		C	PT74B	1		C
C17	PT65A	1		T	PT74A	1		T
A17	PT64B	1		C	PT73B	1		C
B17	PT64A	1		T	PT73A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
VCCIO	VCCIO1	1			VCCIO1	1		
J18	NC	-			PT66B	1		C
J19	NC	-			PT66A	1		T
H17	NC	-			PT65B	1		C
J17	NC	-			PT65A	1		T
F18	NC	-			PT64B	1		C
F17	NC	-			PT64A	1		T
-	-	-			GNDIO1	-		
A16	PT54B	1		C	PT63B	1		C
B16	PT54A	1		T	PT63A	1		T
G17	PT53B	1		C	PT62B	1		C
G16	PT53A	1		T	PT62A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
H16	PT52B	1		C	PT61B	1		C
F16	PT52A	1		T	PT61A	1		T

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AE23	NC	-		
AE5	NC	-		
AE6	NC	-		
AE7	NC	-		
AF20	NC	-		
AF23	NC	-		
AF5	NC	-		
AG23	NC	-		
AG26	NC	-		
D10	NC	-		
E10	NC	-		
E11	NC	-		
F10	NC	-		
F20	NC	-		
F23	NC	-		
F8	NC	-		
G10	NC	-		
G20	NC	-		
G21	NC	-		
G7	NC	-		
G8	NC	-		
G9	NC	-		
H19	NC	-		
H20	NC	-		
H21	NC	-		
H22	NC	-		
H6	NC	-		
H8	NC	-		
H9	NC	-		
J10	NC	-		
J20	NC	-		
J21	NC	-		
J9	NC	-		
K9	NC	-		
R9	NC	-		
U22	NC	-		
W9	NC	-		
N13	VCCPLL	-		
N18	VCCPLL	-		
V13	VCCPLL	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
H33	PR14B	2	RDQ15	C	PR14B	2	RDQ15	C
GNDIO	GNDIO2	-			GNDIO2	-		
H34	PR14A	2	RDQ15	T	PR14A	2	RDQ15	T
J30	PR13B	2	RDQ15	C (LVDS)*	PR13B	2	RDQ15	C (LVDS)*
J29	PR13A	2	RDQ15	T (LVDS)*	PR13A	2	RDQ15	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
J27	PR11B	2	RUM0_SPLLC_IN_A/RDQ15	C (LVDS)*	PR11B	2	RUM0_SPLLC_IN_A/RDQ15	C (LVDS)*
J28	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*
H31	PR9B	2	VREF2_2	C	PR9B	2	VREF2_2	C
GNDIO	GNDIO2	-			GNDIO2	-		
H32	PR9A	2	VREF1_2	T	PR9A	2	VREF1_2	T
VCCIO	VCCIO2	2			VCCIO2	2		
H30	XRES	1			XRES	1		
B33	URC_SQ_VCCRX0	12			URC_SQ_VCCRX0	12		
C33	URC_SQ_HDINP0	12		T	URC_SQ_HDINP0	12		T
B34	URC_SQ_VCCIB0	12			URC_SQ_VCCIB0	12		
C32	URC_SQ_HDINN0	12		C	URC_SQ_HDINN0	12		C
B32	URC_SQ_VCCTX0	12			URC_SQ_VCCTX0	12		
A33	URC_SQ_HDOUTP0	12		T	URC_SQ_HDOUTP0	12		T
C34	URC_SQ_VCCOB0	12			URC_SQ_VCCOB0	12		
A32	URC_SQ_HDOUTN0	12		C	URC_SQ_HDOUTN0	12		C
B31	URC_SQ_VCCTX1	12			URC_SQ_VCCTX1	12		
A31	URC_SQ_HDOUTN1	12		C	URC_SQ_HDOUTN1	12		C
D32	URC_SQ_VCCOB1	12			URC_SQ_VCCOB1	12		
A30	URC_SQ_HDOUTP1	12		T	URC_SQ_HDOUTP1	12		T
B30	URC_SQ_VCCRX1	12			URC_SQ_VCCRX1	12		
C31	URC_SQ_HDINN1	12		C	URC_SQ_HDINN1	12		C
D31	URC_SQ_VCCIB1	12			URC_SQ_VCCIB1	12		
C30	URC_SQ_HDINP1	12		T	URC_SQ_HDINP1	12		T
E29	URC_SQ_VCCAUX33	12			URC_SQ_VCCAUX33	12		
E30	URC_SQ_REFCLKN	12		C	URC_SQ_REFCLKN	12		C
D30	URC_SQ_REFCLKP	12		T	URC_SQ_REFCLKP	12		T
D29	URC_SQ_VCCP	12			URC_SQ_VCCP	12		
C29	URC_SQ_HDINP2	12		T	URC_SQ_HDINP2	12		T
D27	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12		
C28	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C
B29	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12		
A29	URC_SQ_HDOUTP2	12		T	URC_SQ_HDOUTP2	12		T
E28	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12		
A28	URC_SQ_HDOUTN2	12		C	URC_SQ_HDOUTN2	12		C
B28	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12		
A27	URC_SQ_HDOUTN3	12		C	URC_SQ_HDOUTN3	12		C
D26	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		
A26	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
B27	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
C27	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B26	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
C26	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
D28	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		

LatticeECP2M Standard Series Devices, Lead-Free Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20E-5FN484C	304	1.2V	-5	Lead-Free fpBGA	484	COM	20
LFE2M20E-6FN484C	304	1.2V	-6	Lead-Free fpBGA	484	COM	20
LFE2M20E-7FN484C	304	1.2V	-7	Lead-Free fpBGA	484	COM	20
LFE2M20E-5FN256C	140	1.2V	-5	Lead-Free fpBGA	256	COM	20
LFE2M20E-6FN256C	140	1.2V	-6	Lead-Free fpBGA	256	COM	20
LFE2M20E-7FN256C	140	1.2V	-7	Lead-Free fpBGA	256	COM	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35E-5FN672C	410	1.2V	-5	Lead-Free fpBGA	672	COM	35
LFE2M35E-6FN672C	410	1.2V	-6	Lead-Free fpBGA	672	COM	35
LFE2M35E-7FN672C	410	1.2V	-7	Lead-Free fpBGA	672	COM	35
LFE2M35E-5FN484C	303	1.2V	-5	Lead-Free fpBGA	484	COM	35
LFE2M35E-6FN484C	303	1.2V	-6	Lead-Free fpBGA	484	COM	35
LFE2M35E-7FN484C	303	1.2V	-7	Lead-Free fpBGA	484	COM	35
LFE2M35E-5FN256C	140	1.2V	-5	Lead-Free fpBGA	256	COM	35
LFE2M35E-6FN256C	140	1.2V	-6	Lead-Free fpBGA	256	COM	35
LFE2M35E-7FN256C	140	1.2V	-7	Lead-Free fpBGA	256	COM	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50E-5FN900C	410	1.2V	-5	Lead-Free fpBGA	900	COM	50
LFE2M50E-6FN900C	410	1.2V	-6	Lead-Free fpBGA	900	COM	50
LFE2M50E-7FN900C	410	1.2V	-7	Lead-Free fpBGA	900	COM	50
LFE2M50E-5FN672C	372	1.2V	-5	Lead-Free fpBGA	672	COM	50
LFE2M50E-6FN672C	372	1.2V	-6	Lead-Free fpBGA	672	COM	50
LFE2M50E-7FN672C	372	1.2V	-7	Lead-Free fpBGA	672	COM	50
LFE2M50E-5FN484C	270	1.2V	-5	Lead-Free fpBGA	484	COM	50
LFE2M50E-6FN484C	270	1.2V	-6	Lead-Free fpBGA	484	COM	50
LFE2M50E-7FN484C	270	1.2V	-7	Lead-Free fpBGA	484	COM	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70E-5FN1152C	436	1.2V	-5	Lead-Free fpBGA	1152	COM	70
LFE2M70E-6FN1152C	436	1.2V	-6	Lead-Free fpBGA	1152	COM	70
LFE2M70E-7FN1152C	436	1.2V	-7	Lead-Free fpBGA	1152	COM	70
LFE2M70E-5FN900C	416	1.2V	-5	Lead-Free fpBGA	900	COM	70
LFE2M70E-6FN900C	416	1.2V	-6	Lead-Free fpBGA	900	COM	70
LFE2M70E-7FN900C	416	1.2V	-7	Lead-Free fpBGA	900	COM	70

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20SE-5FN484I	304	1.2V	-5	Lead-Free fpBGA	484	Ind	20
LFE2M20SE-6FN484I	304	1.2V	-6	Lead-Free fpBGA	484	Ind	20
LFE2M20SE-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	Ind	20
LFE2M20SE-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	Ind	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35SE-5FN672I	410	1.2V	-5	Lead-Free fpBGA	672	Ind	35
LFE2M35SE-6FN672I	410	1.2V	-6	Lead-Free fpBGA	672	Ind	35
LFE2M35SE-5FN484I	303	1.2V	-5	Lead-Free fpBGA	484	Ind	35
LFE2M35SE-6FN484I	303	1.2V	-6	Lead-Free fpBGA	484	Ind	35
LFE2M35SE-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	Ind	35
LFE2M35SE-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	Ind	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50SE-5FN900I	410	1.2V	-5	Lead-Free fpBGA	900	Ind	50
LFE2M50SE-6FN900I	410	1.2V	-6	Lead-Free fpBGA	900	Ind	50
LFE2M50SE-5FN672I	372	1.2V	-5	Lead-Free fpBGA	672	Ind	50
LFE2M50SE-6FN672I	372	1.2V	-6	Lead-Free fpBGA	672	Ind	50
LFE2M50SE-5FN484I	270	1.2V	-5	Lead-Free fpBGA	484	Ind	50
LFE2M50SE-6FN484I	270	1.2V	-6	Lead-Free fpBGA	484	Ind	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70SE-5FN1152I	436	1.2V	-5	Lead-Free fpBGA	1152	Ind	70
LFE2M70SE-6FN1152I	436	1.2V	-6	Lead-Free fpBGA	1152	Ind	70
LFE2M70SE-5FN900I	416	1.2V	-5	Lead-Free fpBGA	900	Ind	70
LFE2M70SE-6FN900I	416	1.2V	-6	Lead-Free fpBGA	900	Ind	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100SE-5FN1152I	520	1.2V	-5	Lead-Free fpBGA	1152	Ind	100
LFE2M100SE-6FN1152I	520	1.2V	-6	Lead-Free fpBGA	1152	Ind	100
LFE2M100SE-5FN900I	416	1.2V	-5	Lead-Free fpBGA	900	Ind	100
LFE2M100SE-6FN900I	416	1.2V	-6	Lead-Free fpBGA	900	Ind	100

LatticeECP2/M Family Data Sheet Supplemental Information

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For Further Information

A variety of technical notes for the LatticeECP2/M family are available on the Lattice web site at www.latticesemi.com.

- TN1102, LatticeECP2/M sysIO Usage Guide
- TN1103, LatticeECP2/M sysCLOCK PLL Design and Usage Guide
- TN1104, LatticeECP2/M Memory Usage Guide
- TN1105, LatticeECP2/M High-Speed I/O Interface
- TN1106, Power Estimation and Management for LatticeECP2/M Devices
- TN1107, LatticeECP2/M sysDSP Usage Guide
- TN1108, LatticeECP2/M sysCONFIG Usage Guide
- TN1109, LatticeECP2/M Configuration Encryption Usage Guide
- TN1113, LatticeECP2/M Soft Error Detection (SED) Usage Guide
- TN1124, LatticeECP2M SERDES/PCS Usage Guide
- TN1162, LatticeECP2/M Hardware Checklist

For further information about interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: www.pcisig.com